Product-Env-Stewards Product Enviro Compliance NA Product-Env-Stewards@onsemi.com Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM	IPC ASSOCIATION LECTRONICS	Material Comp © Copyright 2005. I industries international and Par	osition De PC, Bannockl n-American c	claration burn, Illinois. A opyright conve	All rights reserved untions.	under both	This docume level parts, the	ent is a declaration	ration of	f the substances npasses all lowe	within the r level m	e manufactu aterials for w	rer listed ite hich the ma	em. No anufact	ote: if the turer has	item is an as engineering	sembly with lo responsibility.
Company name* Company unique ID Unique ID Authority Description Unique ID Authority Description Descri	52-21.1	IPC Web Site for Information on IPC-1752 Standard Form Ty					e *										
Contact Name Title - Contact Product-Env-Stewards P	upplier	Information															
Title - Contact Phone - Contact* Phone - Contact* Product-Env-Stewards Product-Env-Stewards @onsemi.com	ompany n	name*		Company un	ique ID		ī	Unique ID Au	uthority	<i>I</i>			Response	Date	*		
Product-Env-Stewards Authorized Representative* Authorized Representative* Product-Env-Stewards Product Enviro Compliance NA Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM GBPC1206 BR GBPC GPPN 12A 600V 2025-07-03 TSCBE 16949.998 mg Manufacturing Process Information Terminal Plating / Grid Array Material Terminal Base Alloy Product-Env-Stewards@onsemi.com Manufacturing Site Weight* UOM Manufacturing Process Information Manufacturing Site Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Precious metal (e.g. Ag,Au, NiPdAu) (no CU Alloy NA O C 30 seconds 3	semi												2025-07-0	03			
Title - Representative* Product Enviro Compliance Requester Item Number Requester Item N	ontact Na	me		Title - Conta	ct]	Phone - Cont	tact*				Email - C	Contac	et*		
Product-Env-Stewards Product-Env-Stewards	roduct-Eı	nv-Stewards		Product Envi	Product Enviro Compliance			NA					Product-Env-Stewards@onsemi.com				
Requester Item Number	Authorized Representative*				Title - Representative			Phone - Representative*				Email - Representative*					
GBPC1206 BR GBPC GPPN 12A 600V 2025-07-03 TSCBE 16949.998 mg	roduct-Ei	nv-Stewards	Product Envi	Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com						
Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles		Requester Item Number	Mfr Iten	n Number	Mfr Item Name			Effective Da	ite V	ersion	Manufact	uring Site	V	/eight	*	UOM	Unit Type
Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Precious metal (e.g. Ag,Au, NiPdAu) (no CU Alloy NA 0 C 30 seconds 3			GBPC12	206	BR GBPC GPPN	I 12A 600V		2025-07-03		,	ГЅСВЕ		1	6949.9	998	mg	Each
Precious metal (e.g. Ag,Au, NiPdAu) (no CU Alloy NA 0 C 30 seconds 3	lanufac	turing Proccess Informa	tion		,												1
	7	Terminal Plating / Grid Array M	aterial 7	Γerminal Base Alloy J-		J-STD-020 MS	0 MSL Rating		Peak Process Body Temperatur		re Max Time at Peak Temper		Temperatu	re N	re Number of Reflow Cycles		les
			PdAu) (no	CU Alloy		NA		0		С	30		second	ls 3			
Comments	mments																

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		by mass (100 PPM) in homogeneous material for tum (Cr6+), Polybrominated Biphenyls (PBB), Polyl Disobutyl phthalate (DIBP).								
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belie as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.										
RoHS Declaration * 4 - Item(s	s) does not contain RoHS restricted substance	ces per the definition above except for selected exer	nptions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting tempe Exemption: 7c-I Electrical and electronic c	erature type solders (i.e. lead based solder omponents containing lead in a glass or co	r alloys containing 85% by weight or more lead) ceramic other than dielectric ceramic in capacito	rs, e.g. piezoelectronic devices, or in a glass or c	eramic matrix compound.						
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required in Requester) and click on Submit Form to ha		"Accepted" on the Supplier Acceptance drop-do	wn. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature R		,								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Case	2949.3	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		589.8748	mg
			Supplier	Silica (SiO2)	14464-46-1		2064.5603	mg
			Supplier	Phosphorus (P)	7723-14-0		58.9152	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		235.9497	mg
Die	33.561	mg	Supplier	Silicon (Si)	7440-21-3		30.2049	mg
			В	Nickel (Ni)	7440-02-0		0.2181	mg
			Supplier	Gold (Au)	7440-57-5		0.0503	mg
			Supplier	Lead Bisilicate	65997-18-4	7c	3.0876	mg
Die Attach Solder	18.1365	mg	Supplier	Silver (Ag)	7440-22-4		0.4534	mg
			A	Lead (Pb)	7439-92-1	7a	16.7763	mg
			Supplier	Tin (Sn)	7440-31-5		0.9068	mg
Die Attach Solder - Solder Wafer	82.8855	mg	Supplier	Silver (Ag)	7440-22-4		2.0721	mg
			A	Lead (Pb)	7439-92-1		76.6691	mg
			Supplier	Tin (Sn)	7440-31-5		4.1443	mg
Heat Sink	3803.24	mg	Supplier	Aluminum (Al)	7429-90-5		3803.24	mg
Lead Frame	1220.4	mg	Supplier	Iron (Fe)	7439-89-6		0.9763	mg
			Supplier	Copper (Cu)	7440-50-8		1219.1797	mg
			Supplier	Phosphorus (P)	7723-14-0		0.244	mg
Marking Ink	0.5085	mg	Supplier	Silicon Dioxide (SiO2)	112945-52-5		0.0254	mg
			Supplier	1-Hydroxycyclohexyl phenyl ketone	947-19-3		0.0254	mg
			Supplier	Padimate (C14H21NO2)	21245-01-2		0.0509	mg
			Supplier	2-Propenoic acid polymer	53192-18-0		0.3305	mg
			Supplier	Aluminum (Al)	7429-90-5		0.0763	mg
Mold Compound-White	6552.36	mg		Polymer Resin	proprietary data		1092.2784	mg
			Supplier	1,2-Bis(pentabromophenyl) ethane	84852-53-9		382.0026	mg
			Supplier	Brominated epoxy resin	Proprietary Data		1419.8964	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		218.1936	mg
			Supplier	Carbon Black (C)	1333-86-4		54.3846	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		655.236	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		2730.3682	mg
Plating-2	14.916	mg	В	Nickel (Ni)	7440-02-0		14.916	mg
Terminal	2274.69	mg	Supplier	Iron (Fe)	7439-89-6		2.7296	mg

	Supplier	Copper (Cu)	7440-50-8	2270.9822	mg
	Supplier	Phosphorus (P)	7723-14-0	0.9781	mg